

WHAT IS CLAIMED IS:

1. A method comprising:
providing a circuit board having a plurality of holes formed therethrough; and
mounting a spring to an underside of the circuit board, the mounted spring having
5 a plurality of holes each aligned with a respective one of the holes in the circuit board.
2. The method of claim 1, wherein the spring includes at least one spring finger to apply
a load to the underside of the circuit board.
3. The method of claim 2, wherein the spring includes a plurality of bosses, each having
one of the holes of the spring formed therethrough, and the method further comprising:
10 sandwiching each of the bosses of the spring between a respective chassis
standoff and a respective heat sink standoff.
4. The method of claim 3, further comprising simultaneously inserting a fastener through
one of the holes of the circuit board and through a corresponding hole of the spring.
5. The method of claim 2, wherein the plurality of holes of the spring includes four
15 holes.
6. The method of claim 5, wherein the plurality of holes of the circuit board includes
four holes located to define a rectangle.

7. The method of claim 1, wherein the mounting of the spring to the underside of the circuit board includes inserting each of a plurality of board attach fingers of the spring through a respective one of the holes of the circuit board.

8. A spring comprising:

5 a perimeter section including a plurality of sides around an open space;
 a first spring finger extending inwardly and upwardly in an inclined fashion from
a first one of the sides; and

 a second spring finger extending inwardly and upwardly in an inclined fashion
from a second one of the sides that is opposite to the first one of the sides.

10 9. The spring of claim 8, further comprising four board attach fingers each extending
substantially vertically upwardly from the perimeter section, a first one of the board
attach fingers located at a first end of the first one of the sides, a second one of the board
attach fingers located at a second end of the first one of the sides, a third one of the board
attach fingers located at a first end of the second one of the sides, and a fourth one of the
15 board attach fingers located at a second end of the second one of the sides.

10. The spring of claim 9, further comprising four bosses formed in the perimeter
section, each of the bosses located so as to have a respective one of the board attach
fingers extending upwardly therefrom.

20 11. The spring of claim 10, wherein the perimeter section is substantially octagonal, and
includes a pair of long sides that are positioned opposite to each other and that are longer
than the sides from which the first and second spring fingers extend, the perimeter section
further including four short sides that are shorter than the sides from which the first and

second spring fingers extend, each of the short sides joining an end of one of the long sides to an end of one of the sides from which the first and second spring fingers extend.

12. The spring of claim 8, being formed of stainless steel.

13. The spring of claim 8, being formed as a single unitary piece of material.

5 14. The spring of claim 8, further comprising a pair of tape segments, each mounted on an upper surface of a respective one of the first and second spring fingers.

15. An assembly comprising:

 a circuit board; and

 a spring mounted to an underside of the circuit board and having at least one
10 spring finger to apply a load to the underside of the circuit board.

16. The assembly of claim 15, wherein the spring has two spring fingers in contact with the underside of the circuit board.

17. The assembly of claim 16, wherein the spring has four board attach fingers each extending through a respective hole in the circuit board.

15 18. The assembly of claim 17, wherein the spring has four bosses, each having a respective one of the board attach fingers extending upwardly therefrom.

19. A system comprising:

a chassis;

a plurality of chassis standoffs mounted on the chassis;

a heat sink having a plurality of heat sink standoffs mounted on a lower side

5 thereof;

a spring including a plurality of bosses each sandwiched between a respective one of the chassis standoffs and a respective one of the heat sink standoffs; and

a circuit board mounted in the chassis with the spring below the circuit board and the heat sink above the circuit board, the heat sink positioned to conduct heat from an
10 integrated circuit (IC) package mounted on an upper side of the circuit board;

the spring including at least one spring finger to apply a load to an underside of the circuit board at a locus of the IC package.

20. The system of claim 19, wherein the spring includes two spring fingers in contact with the underside of the circuit board.

15 21. The system of claim 20, further comprising four fasteners each extending downwardly through a respective one of the heat sink standoffs, through a respective hole in the circuit board, through a respective hole in the spring, and into a respective one of the chassis standoffs.